

HOSTAFORM® S 9363 XAP®2

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Hostaform® acetal copolymer grade S 9363 XAP®2 is an impact modified grade for demanding applications. Hostaform® S 9363 XAP®2 provides good impact strength while improving modulus and weld line strength over standard impact modified grades, and also exhibits exceptional low emission performance meeting or exceeding the requirements of many automotive markets. Chemical abbreviation according to ISO 1043-1: POM-HI

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	5.5 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.8 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.6 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2000 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	50 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	12 %	ISO 527-1/-2
Flexural modulus	2000 MPa	ISO 178
Charpy impact strength, 23°C	N kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	N kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	13 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	8 kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C	13 kJ/m ²	ISO 180/1A
Izod notched impact strength, -40°C	8.0 kJ/m ²	ISO 180/1A
Hardness, Rockwell, M-scale	65	ISO 2039-2
Poisson's ratio	0.4 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	84 °C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	148 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110 E-6/K	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.25 %	Sim. to ISO 62
Water absorption, 2mm	0.8 %	Sim. to ISO 62
Density	1380 kg/m ³	ISO 1183

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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C
Min. melt temperature	180 °C
Max. melt temperature	200 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	65 °C
Min. mould temperature	60 °C
Max. mould temperature	70 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa

Characteristics

Processing	Injection Moulding, Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified, Low emissions

Additional information

Processing Notes

Pre-Drying

Drying is suggested to help achieve low emission performance and to counter if material has contacted moisture through improper storage and handling.

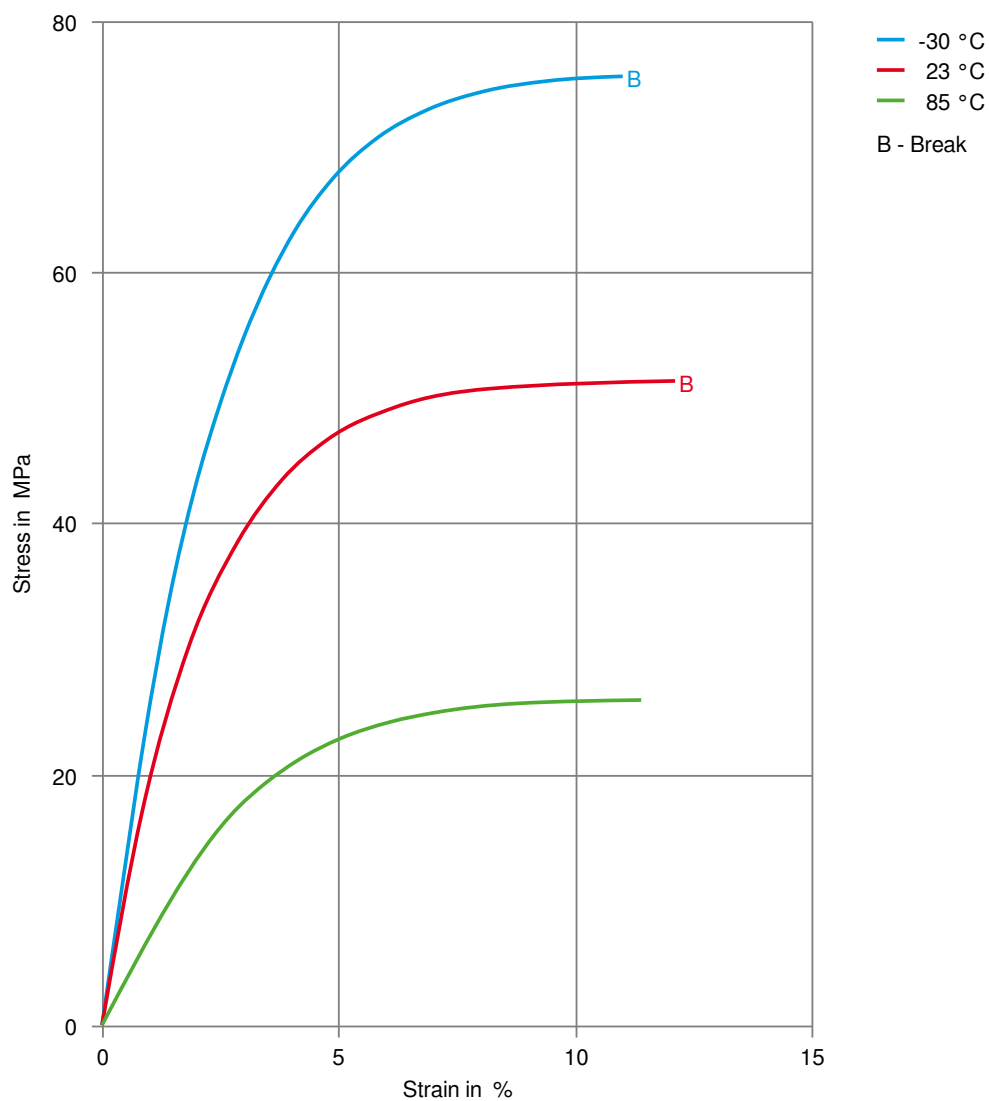
Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Ford	WSF-M4D618-A	Natural
Li Auto	Q/LiA5310020	2021 (V2)
Mercedes-Benz	DBL5404	BQF
Renault	UB15, No Spec, Special Part Approval, See Your CE Account Manager.	
SAIC Motor	SMTC 5 310 020	

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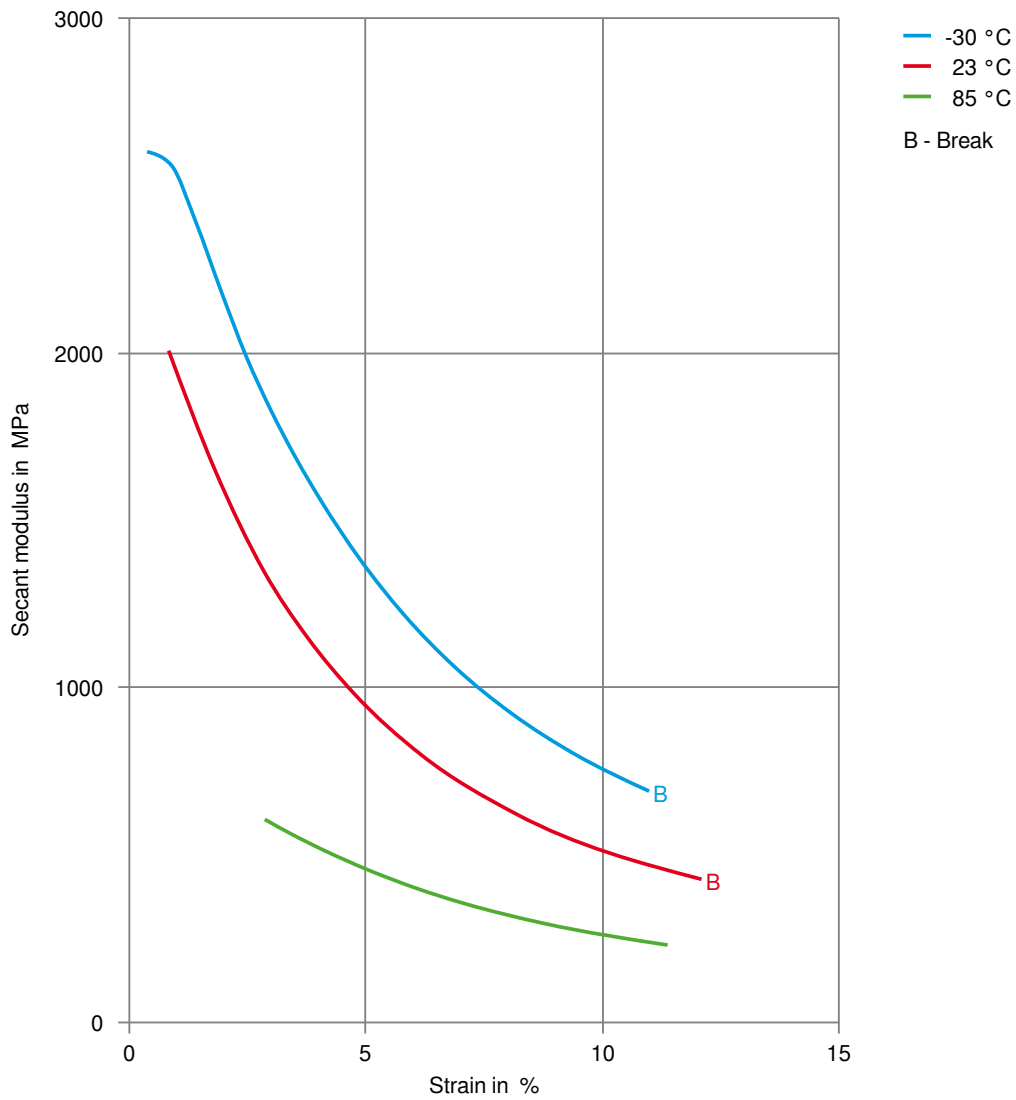
Stress-strain



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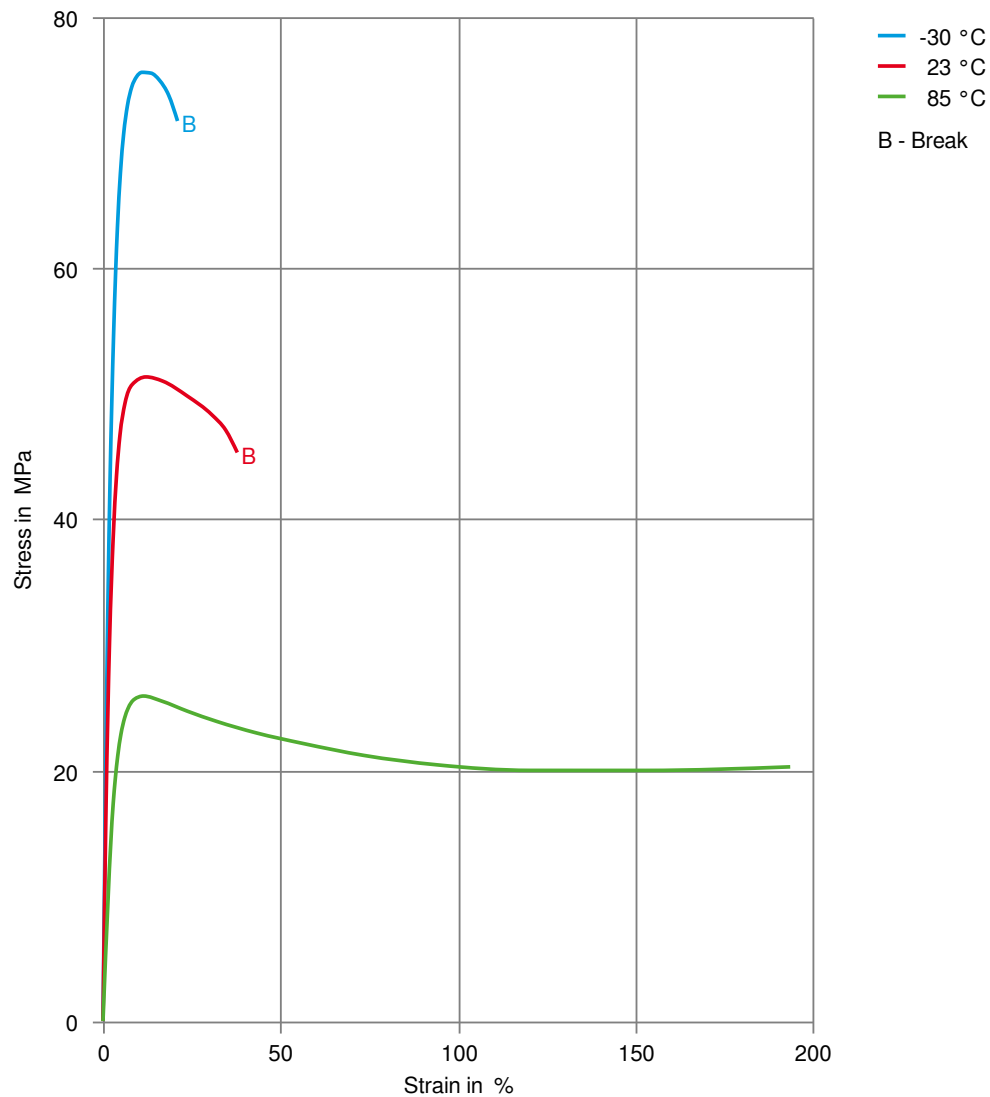
Secant modulus-strain



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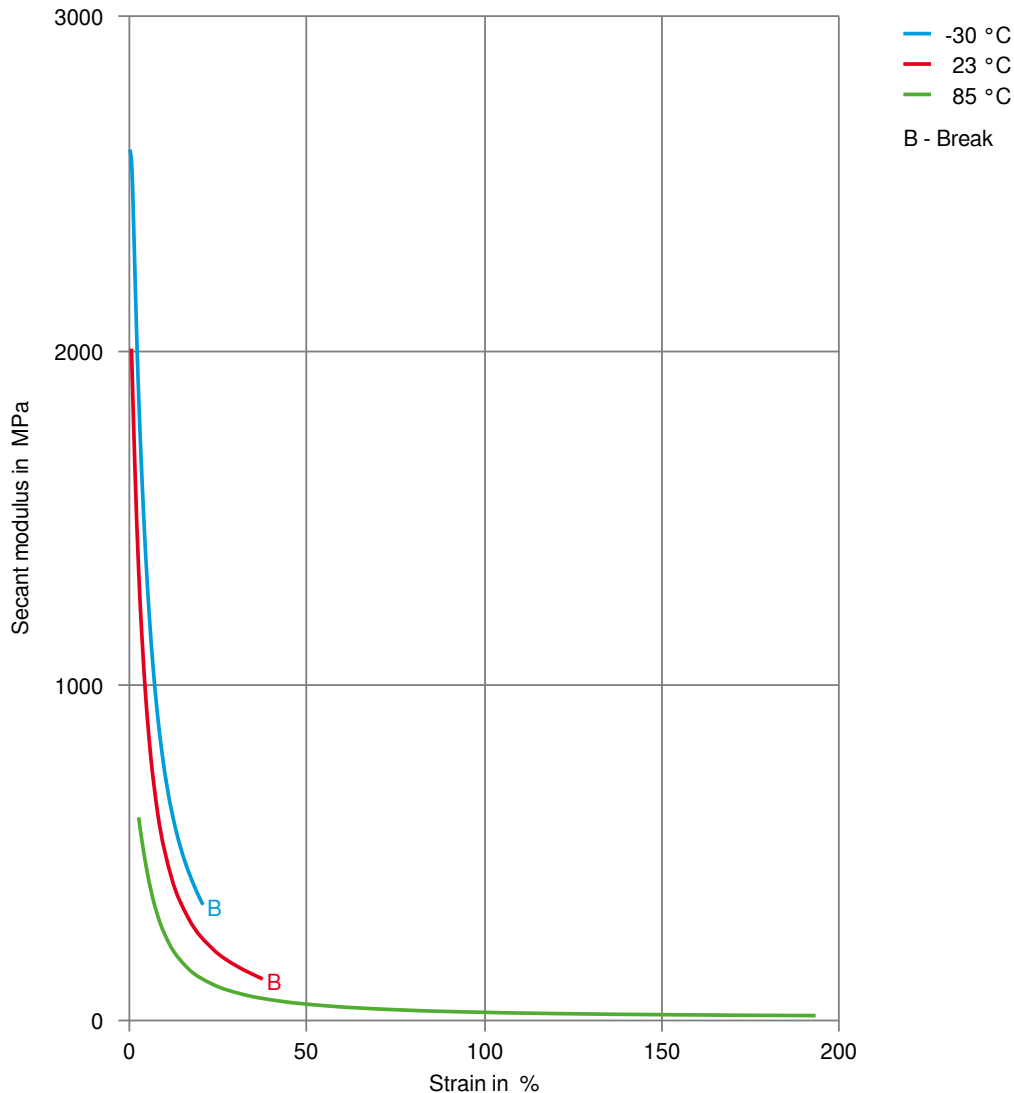
Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min



Printed: 2025-05-30

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Revised: 2024-12-03 Source: Celanese Materials Database

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